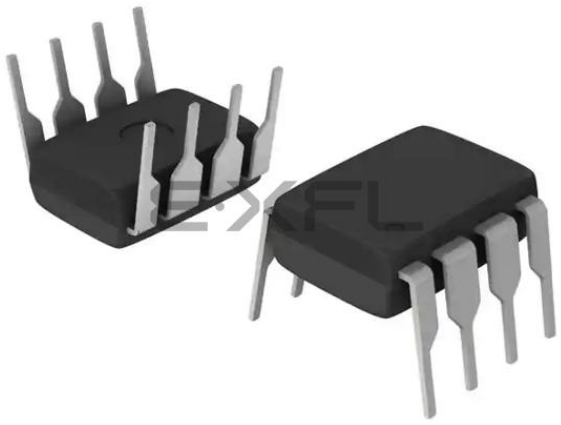

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	5
Program Memory Size	7KB (4K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 4x10b; D/A 1x5b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Through Hole
Package / Case	8-DIP (0.300", 7.62mm)
Supplier Device Package	8-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic12lf1840-e-p

TABLE 1-2: PIC12(L)F1840 PINOUT DESCRIPTION (CONTINUED)

Name	Function	Input Type	Output Type	Description
RA4/AN3/CPS3/OSC2/ CLKOUT/T1OSO/C1IN1-/CLKR/ SDO(1)/CK(1)/TX(1)/P1B(1)/ T1G/MDCIN2	RA4	TTL	CMOS	General purpose I/O.
	AN3	AN	—	ADC Channel 3 input.
	CPS3	AN	—	Capacitive sensing input 3.
	OSC2	—	XTAL	Crystal/Resonator (LP, XT, HS modes).
	CLKOUT	—	CMOS	FOSC/4 output.
	T1OSO	XTAL	XTAL	Timer1 oscillator connection.
	C1IN1-	AN	—	Comparator C1 negative input.
	CLKR	—	CMOS	Clock Reference output.
	SDO	—	CMOS	SPI data output.
	CK	ST	CMOS	USART synchronous clock.
	TX	—	CMOS	USART asynchronous transmit.
	P1B	—	CMOS	PWM output.
	T1G	ST	—	Timer1 Gate input.
	MDCIN2	ST	—	Modulator Carrier Input 2.
RA5/CLKIN/OSC1/T1OSI/ T1CKI/SRNQ/P1A(1)/CCP1(1)/ DT(1)/RX(1)	RA5	TTL	CMOS	General purpose I/O.
	CLKIN	CMOS	—	External clock input (EC mode).
	OSC1	XTAL	—	Crystal/Resonator (LP, XT, HS modes).
	T1OSI	XTAL	XTAL	Timer1 oscillator connection.
	T1CKI	ST	—	Timer1 clock input.
	SRNQ	—	CMOS	SR Latch inverting output.
	P1A	—	CMOS	PWM output.
	CCP1	ST	CMOS	Capture/Compare/PWM 1.
	DT	ST	CMOS	USART synchronous data.
	RX	ST	—	USART asynchronous input.
VDD	VDD	Power	—	Positive supply.
VSS	VSS	Power	—	Ground reference.

Legend: AN = Analog input or output; CMOS = CMOS compatible input or output; OD = Open Drain
TTL = TTL compatible input; ST = Schmitt Trigger input with CMOS levels; I^2C™ = Schmitt Trigger input with I^2C levels
HV = High Voltage; XTAL = Crystal

Note 1: Alternate pin function selected with the APFCON (Register 12-1) register.

3.1.1.2 Indirect Read with FSR

The program memory can be accessed as data by setting bit 7 of the FSRxH register and reading the matching INDFx register. The MOVIW instruction will place the lower eight bits of the addressed word in the W register. Writes to the program memory cannot be performed via the INDF registers. Instructions that access the program memory via the FSR require one extra instruction cycle to complete. Example 3-2 demonstrates accessing the program memory via an FSR.

The High directive will set bit<7> if a label points to a location in program memory.

EXAMPLE 3-2: ACCESSING PROGRAM MEMORY VIA FSR

```
constants
    RETLW DATA0        ;Index0 data
    RETLW DATA1        ;Index1 data
    RETLW DATA2
    RETLW DATA3
my_function
    ;… LOTS OF CODE…
    MOVLW  LOW constants
    MOVWF  FSR1L
    MOVLW  HIGH constants
    MOVWF  FSR1H
    MOVIW 0[FSR1]
;THE PROGRAM MEMORY IS IN W
```

3.2 Data Memory Organization

The data memory is partitioned in 32 memory banks with 128 bytes in a bank. Each bank consists of (Figure 3-2):

- 12 core registers
- 20 Special Function Registers (SFR)
- Up to 80 bytes of General Purpose RAM (GPR)
- 16 bytes of common RAM

The active bank is selected by writing the bank number into the Bank Select Register (BSR). Unimplemented memory will read as '0'. All data memory can be accessed either directly (via instructions that use the file registers) or indirectly via the two File Select Registers (FSR). See **Section 3.6 "Indirect Addressing"** for more information.

3.2.1 CORE REGISTERS

The core registers contain the registers that directly affect the basic operation. The core registers occupy the first 12 addresses of every data memory bank (addresses x00h/x08h through x0Bh/x8Bh). These registers are listed below in Table 3-2. For detailed information, see Table 3-5.

TABLE 3-2: CORE REGISTERS

Addresses	BANKx
x00h or x80h	INDF0
x01h or x81h	INDF1
x02h or x82h	PCL
x03h or x83h	STATUS
x04h or x84h	FSR0L
x05h or x85h	FSR0H
x06h or x86h	FSR1L
x07h or x87h	FSR1H
x08h or x88h	BSR
x09h or x89h	WREG
x0Ah or x8Ah	PCLATH
x0Bh or x8Bh	INTCON

9.2 Low-Power Sleep Mode

The PIC12F1840 device contains an internal Low Dropout (LDO) voltage regulator, which allows the device I/O pins to operate at voltages up to 5.5V while the internal device logic operates at a lower voltage. The LDO and its associated reference circuitry must remain active when the device is in Sleep mode. The PIC12F1840 allows the user to optimize the operating current in Sleep, depending on the application requirements.

A Low-Power Sleep mode can be selected by setting the VREGPM bit of the VREGCON register. With this bit set, the LDO and reference circuitry are placed in a low-power state when the device is in Sleep.

9.2.1 SLEEP CURRENT VS. WAKE-UP TIME

In the default operating mode, the LDO and reference circuitry remain in the normal configuration while in Sleep. The device is able to exit Sleep mode quickly since all circuits remain active. In Low-Power Sleep mode, when waking up from Sleep, an extra delay time is required for these circuits to return to the normal configuration and stabilize.

The Low-Power Sleep mode is beneficial for applications that stay in Sleep mode for long periods of time. The normal mode is beneficial for applications that need to wake from Sleep quickly and frequently.

9.2.2 PERIPHERAL USAGE IN SLEEP

Some peripherals that can operate in Sleep mode will not operate properly with the Low-Power Sleep mode selected. The LDO will remain in the normal power mode when those peripherals are enabled. The Low-Power Sleep mode is intended for use with these peripherals:

- Brown-Out Reset (BOR)
- Watchdog Timer (WDT)
- External interrupt pin/Interrupt-on-change pins
- Timer1 (with external clock source)
- Comparator
- ECCP (Capture mode)

Note:	The PIC12LF1840 does not have a configurable Low-Power Sleep mode. PIC12LF1840 is an unregulated device and is always in the lowest power state when in Sleep, with no wake-up time penalty. This device has a lower maximum V_{DD} and I/O voltage than the PIC12F1840. See **Section 30.0 "Electrical Specifications"** for more information.

10.6 Register Definitions: Watchdog Control

REGISTER 10-1: WDTCON: WATCHDOG TIMER CONTROL REGISTER

U-0	U-0	R/W-0/0	R/W-1/1	R/W-0/0	R/W-1/1	R/W-1/1	R/W-0/0
—	—	WDTPS<4:0>					SWDTEN
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-m/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7-6 **Unimplemented:** Read as '0'

bit 5-1 **WDTPS<4:0>:** Watchdog Timer Period Select bits

Bit Value = Prescale Rate

11111 = Reserved. Results in minimum interval (1:32)
•
•
•
10011 = Reserved. Results in minimum interval (1:32)

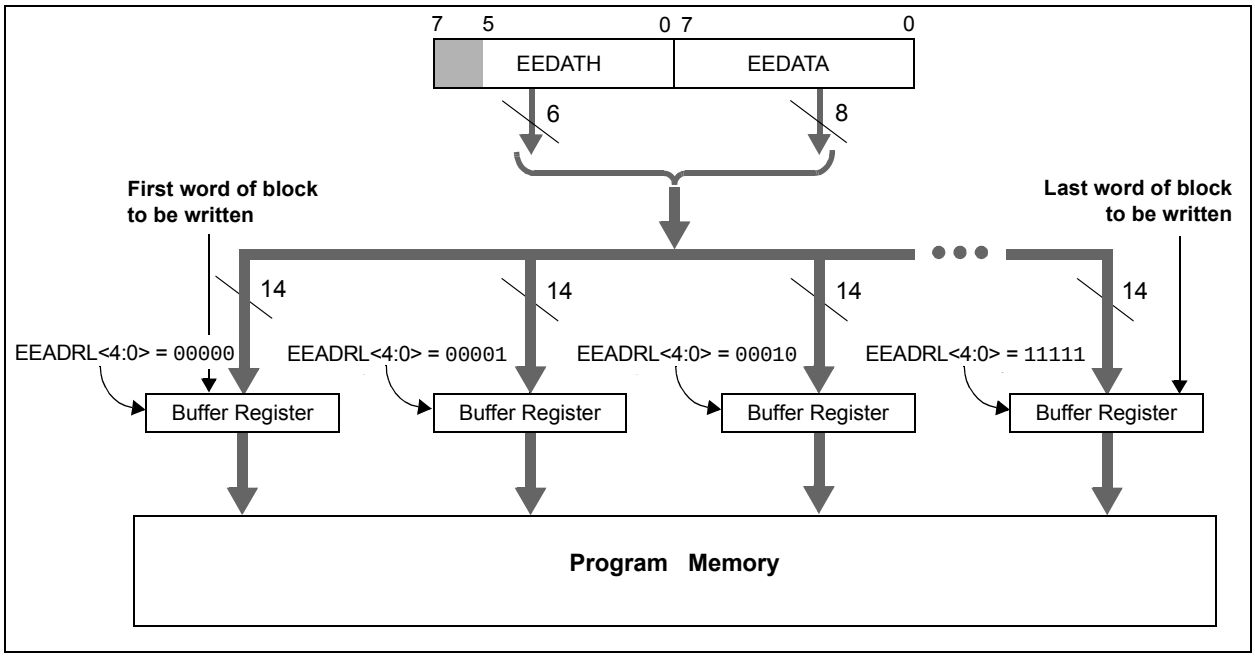
10010 = 1:8388608 (2^{23}) (Interval 256s nominal)
10001 = 1:4194304 (2^{22}) (Interval 128s nominal)
10000 = 1:2097152 (2^{21}) (Interval 64s nominal)
01111 = 1:1048576 (2^{20}) (Interval 32s nominal)
01110 = 1:524288 (2^{19}) (Interval 16s nominal)
01101 = 1:262144 (2^{18}) (Interval 8s nominal)
01100 = 1:131072 (2^{17}) (Interval 4s nominal)
01011 = 1:65536 (Interval 2s nominal) (Reset value)
01010 = 1:32768 (Interval 1s nominal)
01001 = 1:16384 (Interval 512 ms nominal)
01000 = 1:8192 (Interval 256 ms nominal)
00111 = 1:4096 (Interval 128 ms nominal)
00110 = 1:2048 (Interval 64 ms nominal)
00101 = 1:1024 (Interval 32 ms nominal)
00100 = 1:512 (Interval 16 ms nominal)
00011 = 1:256 (Interval 8 ms nominal)
00010 = 1:128 (Interval 4 ms nominal)
00001 = 1:64 (Interval 2 ms nominal)
00000 = 1:32 (Interval 1 ms nominal)

bit 0 **SWDTEN:** Software Enable/Disable for Watchdog Timer bit

If WDTE<1:0> = 00:
This bit is ignored.
If WDTE<1:0> = 01:
1 = WDT is turned on
0 = WDT is turned off
If WDTE<1:0> = 1x:
This bit is ignored.

After the "BSF EECON1,WR" instruction, the processor requires two cycles to set up the write operation. The user must place two NOP instructions after the WR bit is set. The processor will halt internal operations for the typical 2 ms, only during the cycle in which the write takes place (i.e., the last word of the block write). This is not Sleep mode as the clocks and peripherals will continue to run. The processor does not stall when LWLO = 1, loading the write latches. After the write cycle, the processor will resume operation with the third instruction after the EECON1 WRITE instruction.

FIGURE 11-2: BLOCK WRITES TO FLASH PROGRAM MEMORY WITH 32 WRITE LATCHES



EXAMPLE 11-4: ERASING ONE ROW OF PROGRAM MEMORY

```
; This row erase routine assumes the following:
; 1. A valid address within the erase block is loaded in ADDRH:ADDRL
; 2. ADDRH and ADDRL are located in shared data memory 0x70 - 0x7F

        BCF         INTCON,GIE      ; Disable ints so required sequences will execute properly
        BANKSEL     EEADRL
        MOVF        ADDRL,W         ; Load lower 8 bits of erase address boundary
        MOVWF       EEADRL
        MOVF        ADDRH,W         ; Load upper 6 bits of erase address boundary
        MOVWF       EEADRH
        BSF         EECON1,EEPGD    ; Point to program memory
        BCF         EECON1,CFGS     ; Not configuration space
        BSF         EECON1,FREE     ; Specify an erase operation
        BSF         EECON1,WREN     ; Enable writes

Required
Sequence
        MOVLW       55h             ; Start of required sequence to initiate erase
        MOVWF       EECON2          ; Write 55h
        MOVLW       0AAh            ;
        MOVWF       EECON2          ; Write AAh
        BSF         EECON1,WR       ; Set WR bit to begin erase
        NOP                         ; Any instructions here are ignored as processor
                                    ; halts to begin erase sequence
        NOP                         ; Processor will stop here and wait for erase complete.

                                    ; after erase processor continues with 3rd instruction

        BCF         EECON1,WREN     ; Disable writes
        BSF         INTCON,GIE      ; Enable interrupts
```

REGISTER 11-5: EECON1: EEPROM CONTROL 1 REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W/HC-0/0	R/W-x/q	R/W-0/0	R/S/HC-0/0	R/S/HC-0/0
EEPGD	CFGS	LWLO	FREE	WRERR	WREN	WR	RD
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
S = Bit can only be set	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	HC = Bit is cleared by hardware

bit 7 **EEPGD:** Flash Program/Data EEPROM Memory Select bit
- 1 = Accesses program space Flash memory
- 0 = Accesses data EEPROM memory

bit 6 **CFGS:** Flash Program/Data EEPROM or Configuration Select bit
- 1 = Accesses Configuration, User ID and Device ID Registers
- 0 = Accesses Flash Program or data EEPROM Memory

bit 5 **LWLO:** Load Write Latches Only bit

If CFGS = 1 (Configuration space) **OR** CFGS = 0 and EEPGD = 1 (program Flash):
- 1 = The next WR command does not initiate a write; only the program memory latches are updated.
- 0 = The next WR command writes a value from EEDATH:EEDATL into program memory latches and initiates a write of all the data stored in the program memory latches.

If CFGS = 0 and EEPGD = 0: (Accessing data EEPROM)
LWLO is ignored. The next WR command initiates a write to the data EEPROM.

bit 4 **FREE:** Program Flash Erase Enable bit

If CFGS = 1 (Configuration space) **OR** CFGS = 0 and EEPGD = 1 (program Flash):
- 1 = Performs an erase operation on the next WR command (cleared by hardware after completion of erase).
- 0 = Performs a write operation on the next WR command.

If EEPGD = 0 and CFGS = 0: (Accessing data EEPROM)
FREE is ignored. The next WR command will initiate both a erase cycle and a write cycle.

bit 3 **WRERR:** EEPROM Error Flag bit
- 1 = Condition indicates an improper program or erase sequence attempt or termination (bit is set automatically on any set attempt (write '1') of the WR bit).
- 0 = The program or erase operation completed normally.

bit 2 **WREN:** Program/Erase Enable bit
- 1 = Allows program/erase cycles
- 0 = Inhibits programming/erasing of program Flash and data EEPROM

bit 1 **WR:** Write Control bit
- 1 = Initiates a program Flash or data EEPROM program/erase operation. The operation is self-timed and the bit is cleared by hardware once operation is complete. The WR bit can only be set (not cleared) in software.
- 0 = Program/erase operation to the Flash or data EEPROM is complete and inactive.

bit 0 **RD:** Read Control bit
- 1 = Initiates a program Flash or data EEPROM read. Read takes one cycle. RD is cleared in hardware. The RD bit can only be set (not cleared) in software.
- 0 = Does not initiate a program Flash or data EEPROM data read.

15.3 Temperature Output

The output of the circuit is measured using the internal Analog-to-Digital Converter. A channel is reserved for the temperature circuit output. Refer to **Section 16.0 "Analog-to-Digital Converter (ADC) Module"** for detailed information.

Note:	Every time the ADC MUX is changed to the temperature indicator output selection (CHS bit in the ADCCON0 register), wait 500 μsec for the sampling capacitor to fully charge before sampling the temperature indicator output.

15.3.1 ADC ACQUISITION TIME

To ensure accurate temperature measurements, the user must wait at least 200 usec after the ADC input multiplexer is connected to the temperature indicator output before the conversion is performed. In addition, the user must wait 200 usec between sequential conversions of the temperature indicator output.

TABLE 15-2: SUMMARY OF REGISTERS ASSOCIATED WITH THE TEMPERATURE INDICATOR

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on page
FVRCON	FVREN	FVRRDY	TSEN	TSRNG	CDAFVR<1:0>		ADFVR<1:0>		111

Legend: Shaded cells are unused by the temperature indicator module.

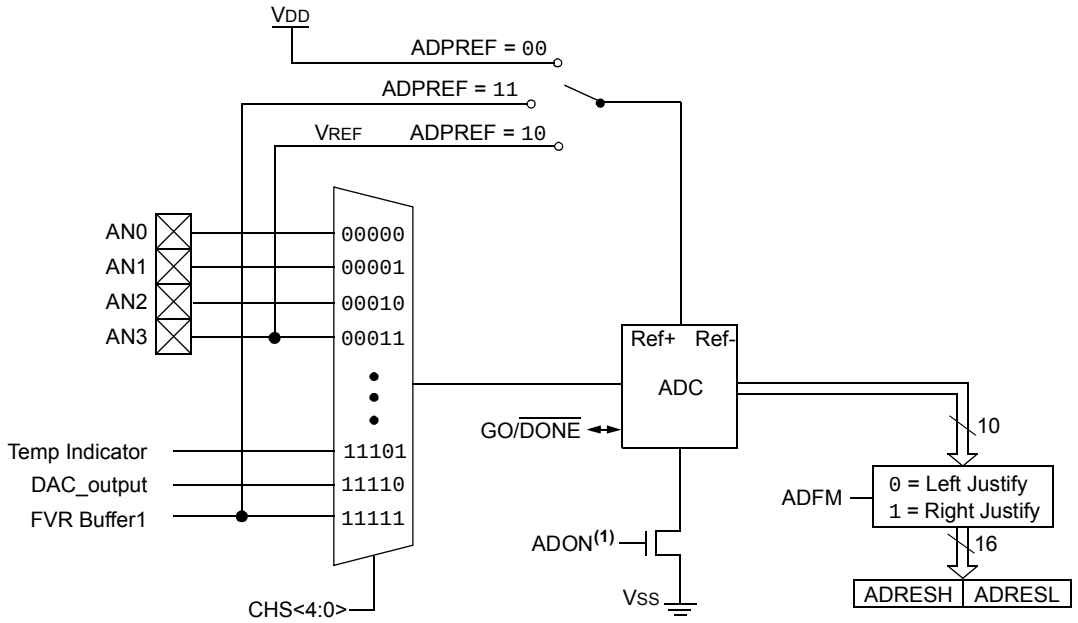
16.0 ANALOG-TO-DIGITAL CONVERTER (ADC) MODULE

The Analog-to-Digital Converter (ADC) allows conversion of an analog input signal to a 10-bit binary representation of that signal. This device uses analog inputs, which are multiplexed into a single sample and hold circuit. The output of the sample and hold is connected to the input of the converter. The converter generates a 10-bit binary result via successive approximation and stores the conversion result into the ADC result registers (ADRESH:ADRESL register pair). Figure 16-1 shows the block diagram of the ADC.

The ADC voltage reference is software selectable to be either internally generated or externally supplied.

The ADC can generate an interrupt upon completion of a conversion. This interrupt can be used to wake-up the device from Sleep.

FIGURE 16-1: ADC BLOCK DIAGRAM



Note 1: When ADON = 0, all multiplexer inputs are disconnected.

20.2 Register Definitions: Option Register

REGISTER 20-1: OPTION_REG: OPTION REGISTER

R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1	R/W-1/1
$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
'1' = Bit is set	'0' = Bit is cleared	

bit 7 **$\overline{\text{WPUEN}}$:** Weak Pull-Up Enable bit
1 = All weak pull-ups are disabled (except $\overline{\text{MCLR}}$, if it is enabled)
0 = Weak pull-ups are enabled by individual WPUA latch values

bit 6 **INTEDG:** Interrupt Edge Select bit
1 = Interrupt on rising edge of INT pin
0 = Interrupt on falling edge of INT pin

bit 5 **TMR0CS:** Timer0 Clock Source Select bit
1 = Transition on T0CKI pin
0 = Internal instruction cycle clock (FOSC/4)

bit 4 **TMR0SE:** Timer0 Source Edge Select bit
1 = Increment on high-to-low transition on T0CKI pin
0 = Increment on low-to-high transition on T0CKI pin

bit 3 **PSA:** Prescaler Assignment bit
1 = Prescaler is not assigned to the Timer0 module
0 = Prescaler is assigned to the Timer0 module

bit 2-0 **PS<2:0>:** Prescaler Rate Select bits

Bit Value	Timer0 Rate
000	1 : 2
001	1 : 4
010	1 : 8
011	1 : 16
100	1 : 32
101	1 : 64
110	1 : 128
111	1 : 256

TABLE 20-1: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER0

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
CPSCON0	CPSON	CPSRM	—	—	CPSRNG<1:0>		CPSOUT	T0XCS	282
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	72
OPTION_REG	$\overline{\text{WPUEN}}$	INTEDG	TMR0CS	TMR0SE	PSA	PS<2:0>			145
TMR0	Timer0 Module Register								143*
TRISA	—	—	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	102

Legend: — = Unimplemented locations, read as '0'. Shaded cells are not used by the Timer0 module.
* Page provides register information.

21.3 Timer1 Prescaler

Timer1 has four prescaler options allowing 1, 2, 4 or 8 divisions of the clock input. The T1CKPS bits of the T1CON register control the prescale counter. The prescale counter is not directly readable or writable; however, the prescaler counter is cleared upon a write to TMR1H or TMR1L.

21.4 Timer1 Oscillator

A dedicated low-power 32.768 kHz oscillator circuit is built-in between pins T1OSI (input) and T1OSO (amplifier output). This internal circuit is to be used in conjunction with an external 32.768 kHz crystal.

The oscillator circuit is enabled by setting the T1OSCEN bit of the T1CON register. The oscillator will continue to run during Sleep.

Note:	The oscillator requires a start-up and stabilization time before use. Thus, T1OSCEN should be set and a suitable delay observed prior to using Timer1. A suitable delay similar to the OST delay can be implemented in software by clearing the TMR1IF bit then presetting the TMR1H:TMR1L register pair to FC00h. The TMR1IF flag will be set when 1024 clock cycles have elapsed, thereby indicating that the oscillator is running and reasonably stable.

21.5 Timer1 Operation in Asynchronous Counter Mode

If the control bit $\overline{\text{T1SYNC}}$ of the T1CON register is set, the external clock input is not synchronized. The timer increments asynchronously to the internal phase clocks. If the external clock source is selected then the timer will continue to run during Sleep and can generate an interrupt on overflow, which will wake-up the processor. However, special precautions in software are needed to read/write the timer (see **Section 21.5.1 "Reading and Writing Timer1 in Asynchronous Counter Mode"**).

Note:	When switching from synchronous to asynchronous operation, it is possible to skip an increment. When switching from asynchronous to synchronous operation, it is possible to produce an additional increment.

21.5.1 READING AND WRITING TIMER1 IN ASYNCHRONOUS COUNTER MODE

Reading TMR1H or TMR1L while the timer is running from an external asynchronous clock will ensure a valid read (taken care of in hardware). However, the user should keep in mind that reading the 16-bit timer in two 8-bit values itself, poses certain problems, since the timer may overflow between the reads.

For writes, it is recommended that the user simply stop the timer and write the desired values. A write contention may occur by writing to the timer registers, while the register is incrementing. This may produce an unpredictable value in the TMR1H:TMR1L register pair.

21.6 Timer1 Gate

Timer1 can be configured to count freely or the count can be enabled and disabled using Timer1 gate circuitry. This is also referred to as Timer1 Gate Enable.

Timer1 gate can also be driven by multiple selectable sources.

21.6.1 TIMER1 GATE ENABLE

The Timer1 Gate Enable mode is enabled by setting the TMR1GE bit of the T1GCON register. The polarity of the Timer1 Gate Enable mode is configured using the T1GPOL bit of the T1GCON register.

When Timer1 Gate Enable mode is enabled, Timer1 will increment on the rising edge of the Timer1 clock source. When Timer1 Gate Enable mode is disabled, no incrementing will occur and Timer1 will hold the current count. See Figure 21-3 for timing details.

TABLE 21-3: TIMER1 GATE ENABLE SELECTIONS

T1CLK	T1GPOL	T1G	Timer1 Operation
↑	0	0	Counts
↑	0	1	Holds Count
↑	1	0	Holds Count
↑	1	1	Counts

21.6.2 TIMER1 GATE SOURCE SELECTION

Timer1 gate source selections are shown in Table 21-4. Source selection is controlled by the T1GSS bits of the T1GCON register. The polarity for each available source is also selectable. Polarity selection is controlled by the T1GPOL bit of the T1GCON register.

TABLE 21-4: TIMER1 GATE SOURCES

T1GSS	Timer1 Gate Source
00	Timer1 Gate Pin
01	Overflow of Timer0 (TMR0 increments from FFh to 00h)
10	Comparator 1 Output sync_C1OUT (optionally Timer1 synchronized output)
11	Reserved

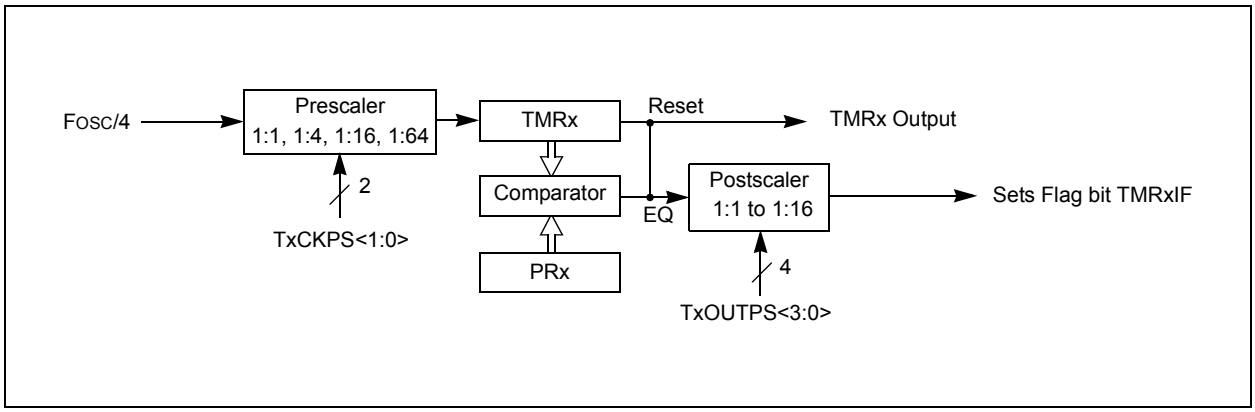
22.0 TIMER2 MODULE

The Timer2 module incorporates the following features:

- 8-bit Timer and Period registers (TMR2 and PR2, respectively)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4, 1:16, and 1:64)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match with PR2, respectively
- Optional use as the shift clock for the MSSP1 modules

See Figure 22-1 for a block diagram of Timer2.

FIGURE 22-1: TIMER2 BLOCK DIAGRAM

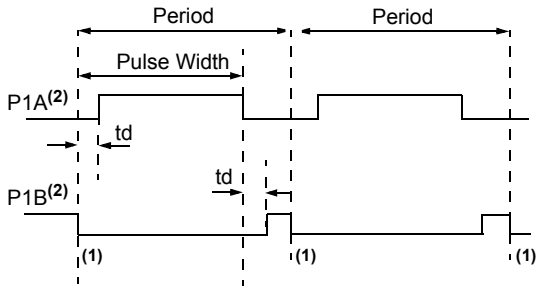


24.4.4 PROGRAMMABLE DEAD-BAND DELAY MODE

In half-bridge applications where all power switches are modulated at the PWM frequency, the power switches normally require more time to turn off than to turn on. If both the upper and lower power switches are switched at the same time (one turned on, and the other turned off), both switches may be on for a short period of time until one switch completely turns off. During this brief interval, a very high current (*shoot-through current*) will flow through both power switches, shorting the bridge supply. To avoid this potentially destructive shoot-through current from flowing during switching, turning on either of the power switches is normally delayed to allow the other switch to completely turn off.

In Half-Bridge mode, a digitally programmable dead-band delay is available to avoid shoot-through current from destroying the bridge power switches. The delay occurs at the signal transition from the non-active state to the active state. See Figure 24-12 for illustration. The lower seven bits of the associated PWM1CON register (Register 24-3) sets the delay period in terms of microcontroller instruction cycles (TCY or 4 TOSC).

FIGURE 24-12: EXAMPLE OF HALF-BRIDGE PWM OUTPUT



td = Dead-Band Delay

Note 1: At this time, the TMR2 register is equal to the PR2 register.

2: Output signals are shown as active-high.

FIGURE 24-13: EXAMPLE OF HALF-BRIDGE APPLICATIONS

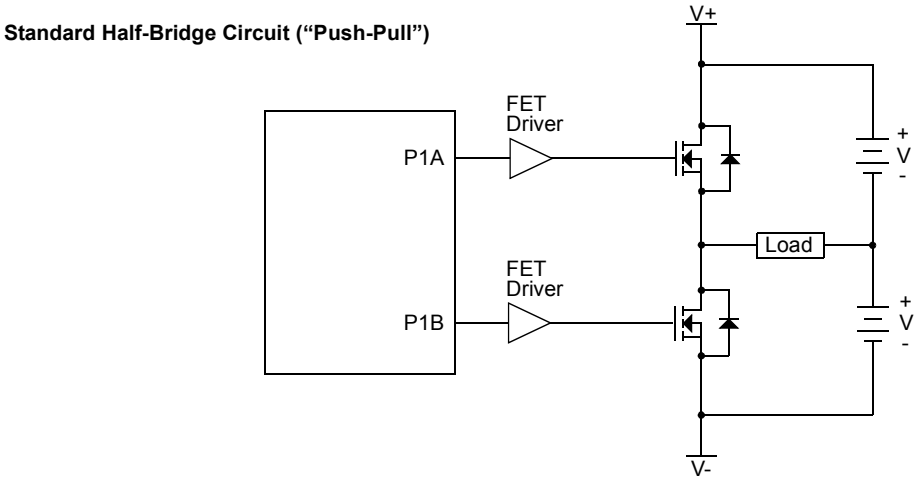


FIGURE 25-3: MSSP1 BLOCK DIAGRAM (I^2C™ SLAVE MODE)

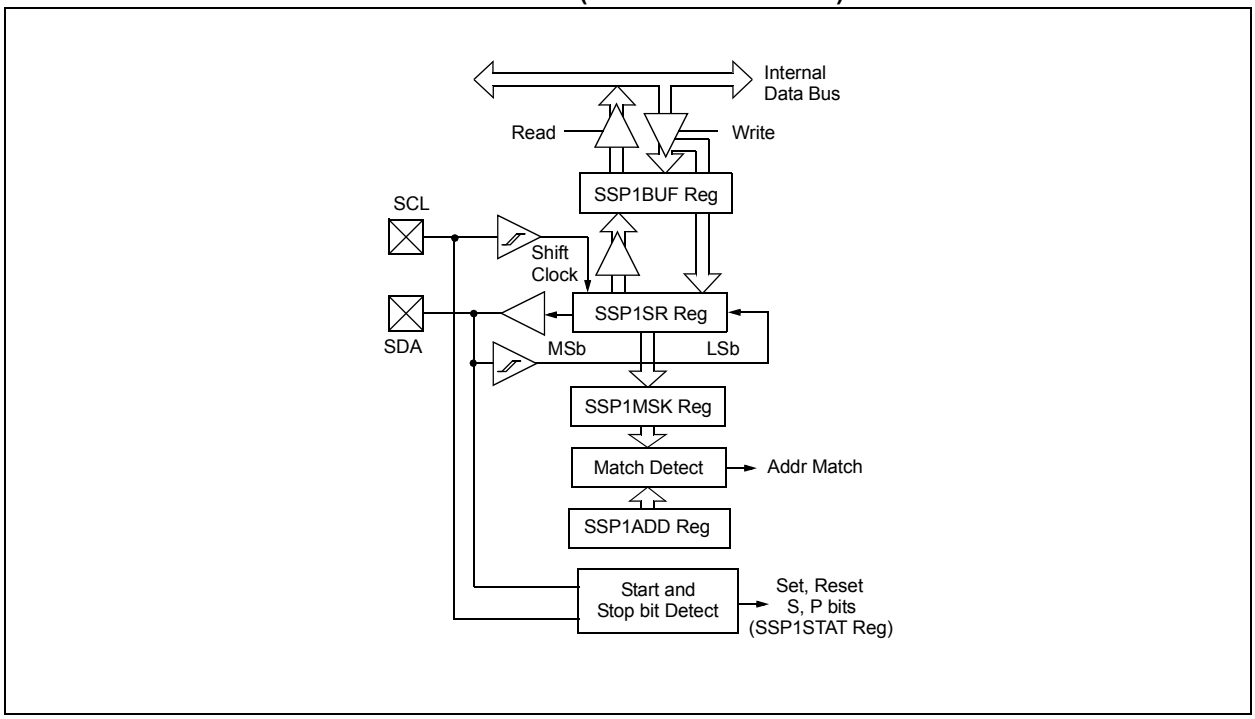
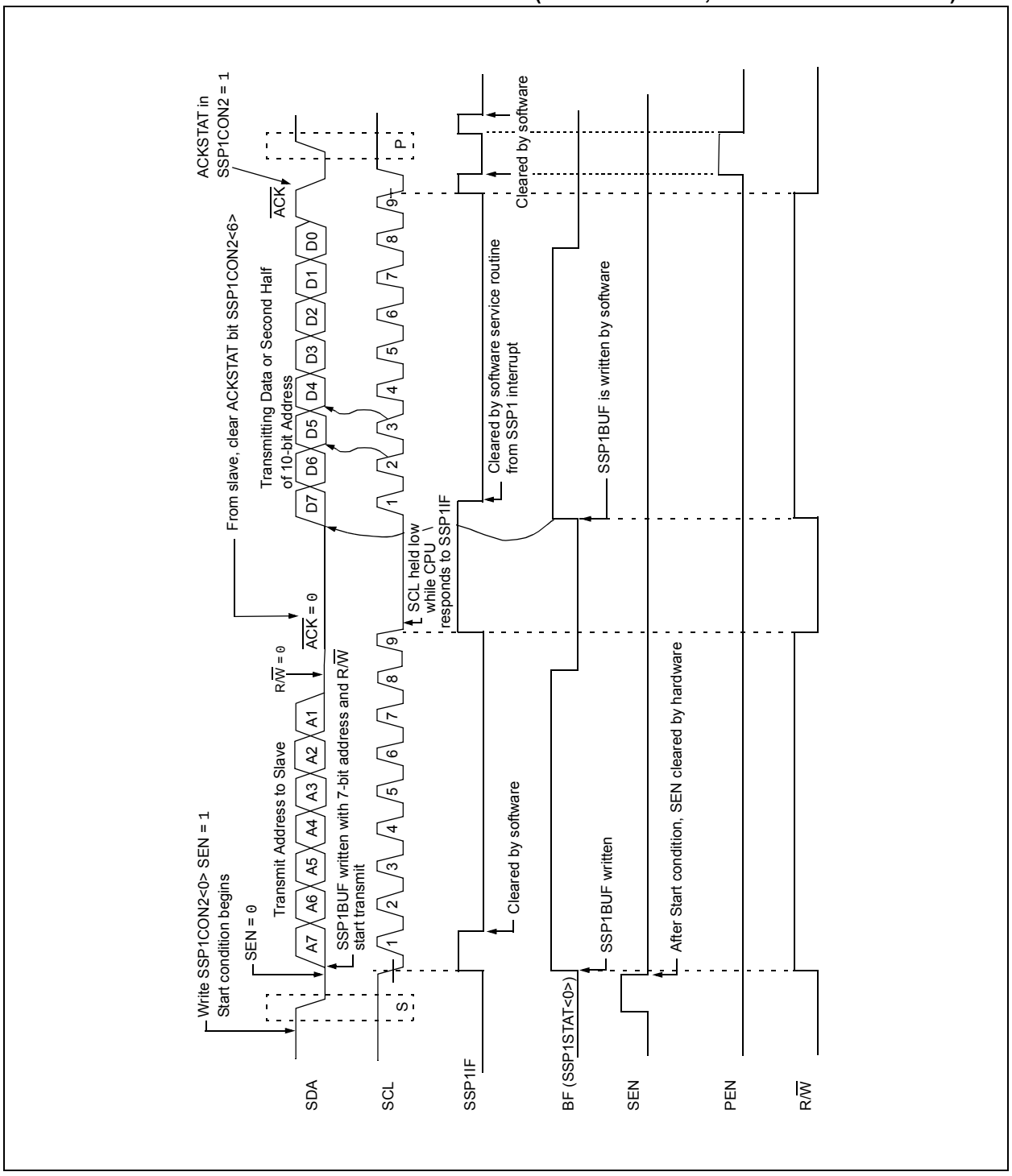


FIGURE 25-28: I²C MASTER MODE WAVEFORM (TRANSMISSION, 7 OR 10-BIT ADDRESS)



25.6.13.2 Bus Collision During a Repeated Start Condition

During a Repeated Start condition, a bus collision occurs if:

a) A low level is sampled on SDA when SCL goes from low level to high level (Case 1).
b) SCL goes low before SDA is asserted low, indicating that another master is attempting to transmit a data '1' (Case 2).

When the user releases SDA and the pin is allowed to float high, the BRG is loaded with SSP1ADD and counts down to zero. The SCL pin is then deasserted and when sampled high, the SDA pin is sampled.

If SDA is low, a bus collision has occurred (i.e., another master is attempting to transmit a data '0', Figure 25-36). If SDA is sampled high, the BRG is reloaded and begins counting. If SDA goes from high-to-low before the BRG times out, no bus collision occurs because no two masters can assert SDA at exactly the same time.

If SCL goes from high-to-low before the BRG times out and SDA has not already been asserted, a bus collision occurs. In this case, another master is attempting to transmit a data '1' during the Repeated Start condition, see Figure 25-37.

If, at the end of the BRG time-out, both SCL and SDA are still high, the SDA pin is driven low and the BRG is reloaded and begins counting. At the end of the count, regardless of the status of the SCL pin, the SCL pin is driven low and the Repeated Start condition is complete.

FIGURE 25-36: BUS COLLISION DURING A REPEATED START CONDITION (CASE 1)

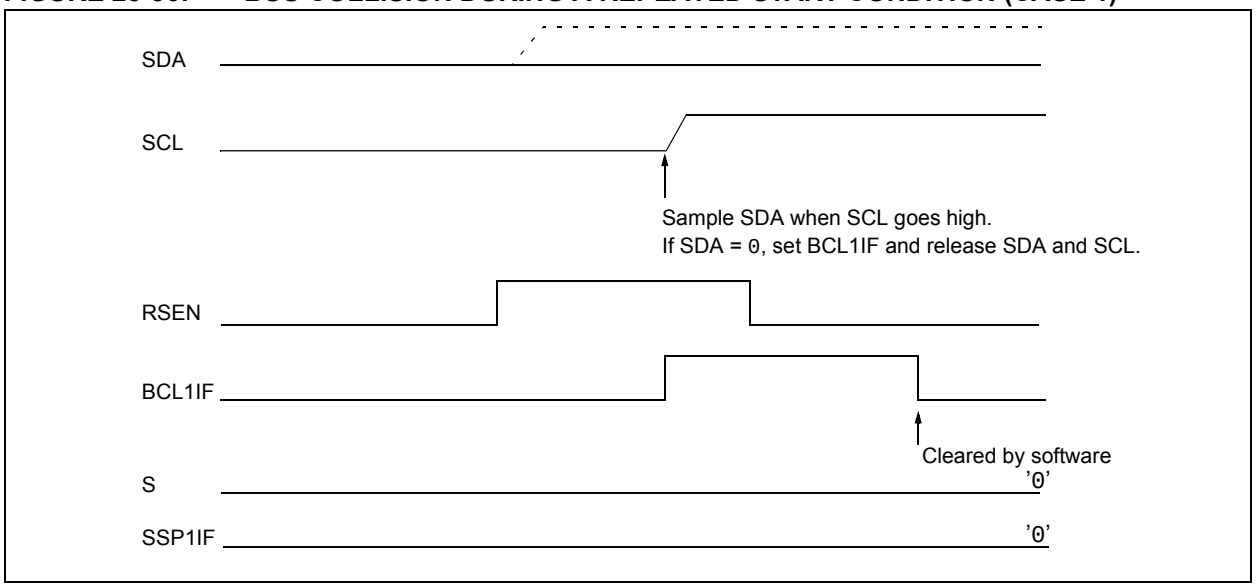
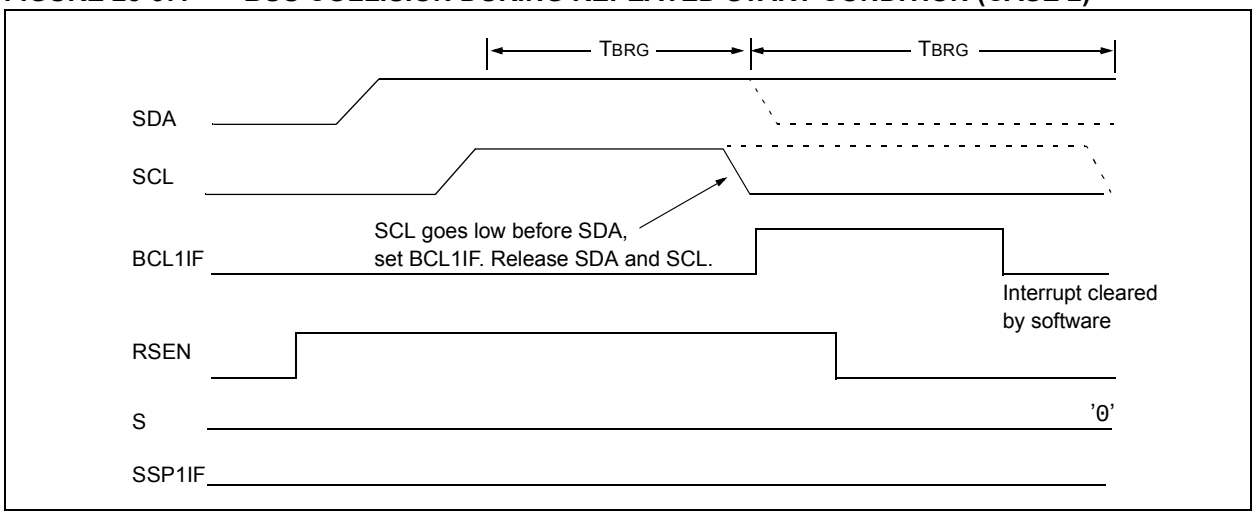


FIGURE 25-37: BUS COLLISION DURING REPEATED START CONDITION (CASE 2)



26.1.1.5 TSR Status

The TRMT bit of the TXSTA register indicates the status of the TSR register. This is a read-only bit. The TRMT bit is set when the TSR register is empty and is cleared when a character is transferred to the TSR register from the TXREG. The TRMT bit remains clear until all bits have been shifted out of the TSR register. No interrupt logic is tied to this bit, so the user has to poll this bit to determine the TSR status.

Note:	The TSR register is not mapped in data memory, so it is not available to the user.

26.1.1.6 Transmitting 9-Bit Characters

The EUSART supports 9-bit character transmissions. When the TX9 bit of the TXSTA register is set, the EUSART will shift nine bits out for each character transmitted. The TX9D bit of the TXSTA register is the ninth, and Most Significant, data bit. When transmitting 9-bit data, the TX9D data bit must be written before writing the eight Least Significant bits into the TXREG. All nine bits of data will be transferred to the TSR shift register immediately after the TXREG is written.

A special 9-bit Address mode is available for use with multiple receivers. See **Section 26.1.2.7 "Address Detection"** for more information on the address mode.

26.1.1.7 Asynchronous Transmission Set-up:

1. Initialize the SPBRGH, SPBRGL register pair and the BRGH and BRG16 bits to achieve the desired baud rate (see **Section 26.4 "EUSART Baud Rate Generator (BRG)"**).
2. Enable the asynchronous serial port by clearing the SYNC bit and setting the SPEN bit.
3. If 9-bit transmission is desired, set the TX9 control bit. A set ninth data bit will indicate that the eight Least Significant data bits are an address when the receiver is set for address detection.
4. Set SCKP bit if inverted transmit is desired.
5. Enable the transmission by setting the TXEN control bit. This will cause the TXIF interrupt bit to be set.
6. If interrupts are desired, set the TXIE interrupt enable bit of the PIE1 register. An interrupt will occur immediately provided that the GIE and PEIE bits of the INTCON register are also set.
7. If 9-bit transmission is selected, the ninth bit should be loaded into the TX9D data bit.
8. Load 8-bit data into the TXREG register. This will start the transmission.

FIGURE 26-3: ASYNCHRONOUS TRANSMISSION

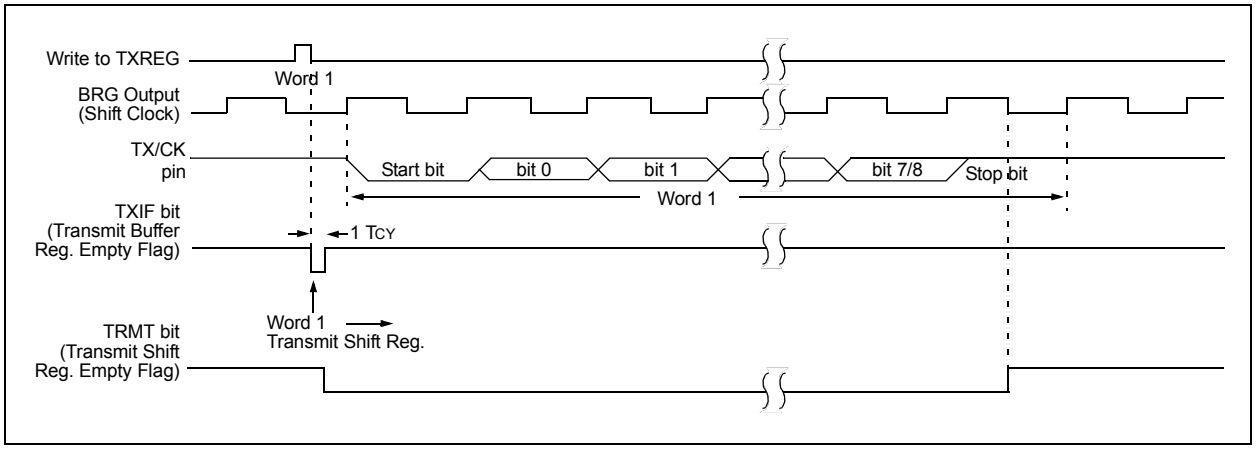


TABLE 30-5: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated) Operating Temperature -40°C ≤ TA ≤ +125°C							
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{\text{MCLR}}$ Pulse Width (low)	2	—	—	μs	
31	TWDTLP	Low-Power Watchdog Timer Time-out Period	10	16	27	ms	VDD = 3.3V-5V, 1:16 Prescaler used
32	TOST	Oscillator Start-up Timer Period **(Note 1)**	—	1024	—	Tosc	
33*	TPWRT	Power-up Timer Period, $\overline{\text{PWRTE}}$ = 0	40	65	140	ms	
34*	TIOZ	I/O high-impedance from $\overline{\text{MCLR}}$ Low or Watchdog Timer Reset	—	—	2.0	μs	
35	VBOR	Brown-out Reset Voltage **(Note 2)**	2.55 2.35 1.80	2.70 2.45 1.90	2.85 2.58 2.00	V V V	BORV = 0, PIC12(L)F1840 BORV = 1, PIC12F1840 PIC12LF1840
37*	VHYST	Brown-out Reset Hysteresis	0	25	75	mV	-40°C to +85°C
38*	TBORDC	Brown-out Reset DC Response Time	1	3	35	μs	VDD ≤ VBOR

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: By design, the Oscillator Start-up Timer (OST) counts the first 1024 cycles, independent of frequency.

2: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 μF and 0.01 μF values in parallel are recommended.

TABLE 30-14: SPI MODE REQUIREMENTS

Param No.	Symbol	Characteristic		Min.	Typ†	Max.	Units	Conditions
SP70*	TssL2scH, TssL2scL	$\overline{SS}\downarrow$ to SCK$\downarrow$ or SCK$\uparrow$ input		2.25 Tcy	—	—	ns	
SP71*	TscH	SCK input high time (Slave mode)		Tcy + 20	—	—	ns	
SP72*	TscL	SCK input low time (Slave mode)		Tcy + 20	—	—	ns	
SP73*	TdiV2scH, TdiV2scL	Setup time of SDI data input to SCK edge		100	—	—	ns	
SP74*	TscH2diL, TscL2diL	Hold time of SDI data input to SCK edge		100	—	—	ns	
SP75*	TdoR	SDO data output rise time	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP76*	TdoF	SDO data output fall time		—	10	25	ns	
SP77*	TssH2doZ	$\overline{SS}\uparrow$ to SDO output high-impedance		10	—	50	ns	
SP78*	TscR	SCK output rise time (Master mode)	3.0-5.5V	—	10	25	ns	
			1.8-5.5V	—	25	50	ns	
SP79*	TscF	SCK output fall time (Master mode)		—	10	25	ns	
SP80*	TscH2doV, TscL2doV	SDO data output valid after SCK edge	3.0-5.5V	—	—	50	ns	
			1.8-5.5V	—	—	145	ns	
SP81*	TdoV2scH, TdoV2scL	SDO data output setup to SCK edge		Tcy	—	—	ns	
SP82*	TssL2doV	SDO data output valid after $\overline{SS}\downarrow$ edge		—	—	50	ns	
SP83*	TscH2ssH, TscL2ssH	$\overline{SS}\uparrow$ after SCK edge		1.5Tcy + 40	—	—	ns	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

TABLE 30-19: DC CHARACTERISTICS FOR PIC12F1840-H (High Temp.)

PIC12F1840			Standard Operating Conditions: (unless otherwise stated) Operating Temperature: -40°C ≤ TA ≤ +150°C for High Temperature				
Param No.	**Sym.**	**Characteristics**	**Min.**	**Typ.**	**Max.**	**Units**	**Condition**
D001	VDD	Supply Voltage	2.5	—	5.5	V	FOSC ≤ 32 MHz **(Note 2)**
D002*	VDR	RAM Data Retention Voltage(1)	2.1	—	5.5	V	Device in Sleep mode
D003	VADFVR	Fixed Voltage Reference Voltage for ADC	-10	—	8	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V
D003A	VCDAFVR	Fixed Voltage Reference Voltage for ADC	-13	—	9	%	1.024V, VDD ≥ 2.5V 2.048V, VDD ≥ 2.5V 4.096V, VDD ≥ 4.75V

* These parameters are characterized but not tested.

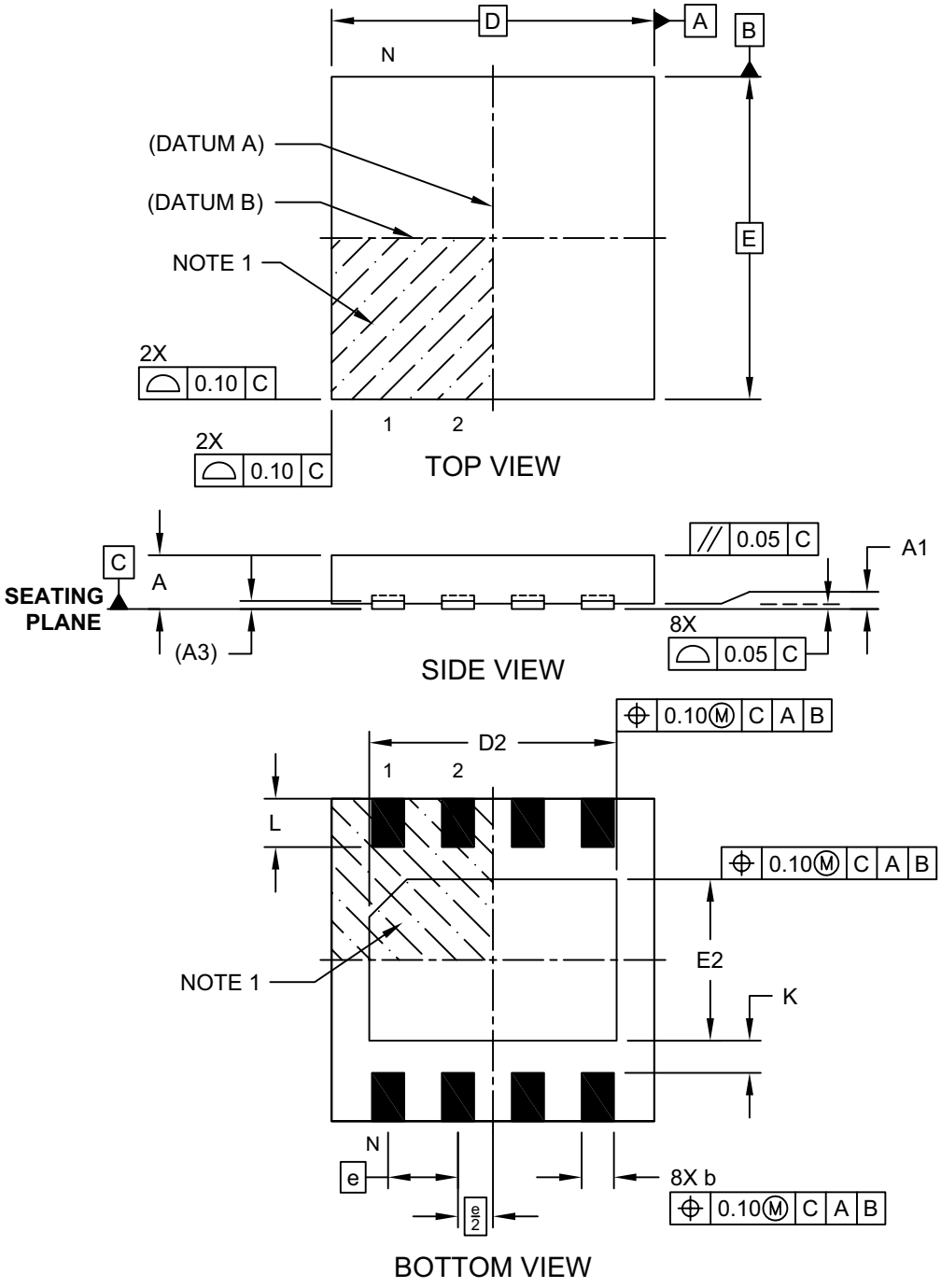
† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in Sleep mode without losing RAM data.

2: PLL required for 32 MHz operation.

8-Lead Ultra Thin Plastic Dual Flat, No Lead Package (RF) - 3x3x0.50 mm Body [UDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



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